



# VND830LSP-E

## DOUBLE CHANNEL HIGH SIDE DRIVER

**Table 1. General Features**

| Type        | R <sub>DS(on)</sub> | I <sub>out</sub> | V <sub>CC</sub> |
|-------------|---------------------|------------------|-----------------|
| VND830LSP-E | 60mΩ (*)            | 18A (*)          | 36V             |

(\*) Per each channel

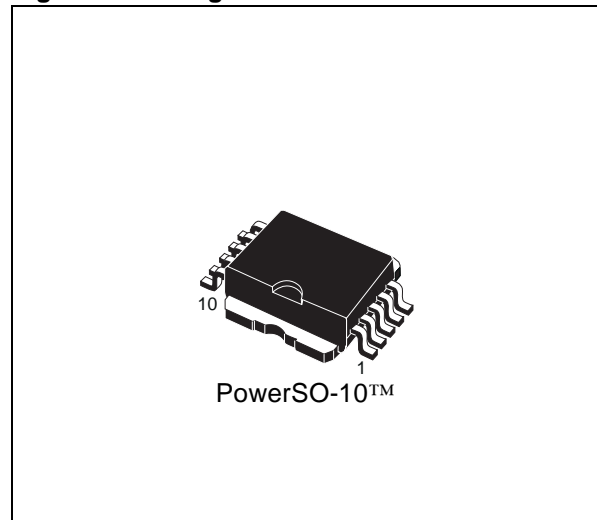
- CMOS COMPATIBLE INPUTS
- OPEN DRAIN STATUS OUTPUTS
- ON STATE OPEN LOAD DETECTION
- OFF STATE OPEN LOAD DETECTION
- SHORTED LOAD PROTECTION
- UNDERVOLTAGE AND OVERVOLTAGE SHUTDOWN
- LOSS OF GROUND PROTECTION
- VERY LOW STAND-BY CURRENT
- REVERSE BATTERY PROTECTION (\*\*)
- IN COMPLIANCE WITH THE 2002/95/EC EUROPEAN DIRECTIVE

### DESCRIPTION

The VND830LSP-E is a monolithic device made by using STMicroelectronics VIPower M0-3 Technology, intended for driving any kind of load with one side connected to ground.

Active V<sub>CC</sub> pin voltage clamp protects the device against low energy spikes (see ISO7637 transient

**Figure 1. Package**



compatibility table). Active current limitation combined with thermal shutdown and automatic restart protects the device against overload. The device detects open load condition both in on and off state. The openload threshold is aimed at detecting the 5W/12V standard bulb as an openload fault in the on state. Device automatically turns off in case of ground pin disconnection.

**Table 2. Order Codes**

| Package     | Tube        | Tape and Reel |
|-------------|-------------|---------------|
| PowerSO-10™ | VND830LSP-E | VND830LSPTR-E |

Note: (\*\*) See application schematic at page 9

Figure 2. Block Diagram

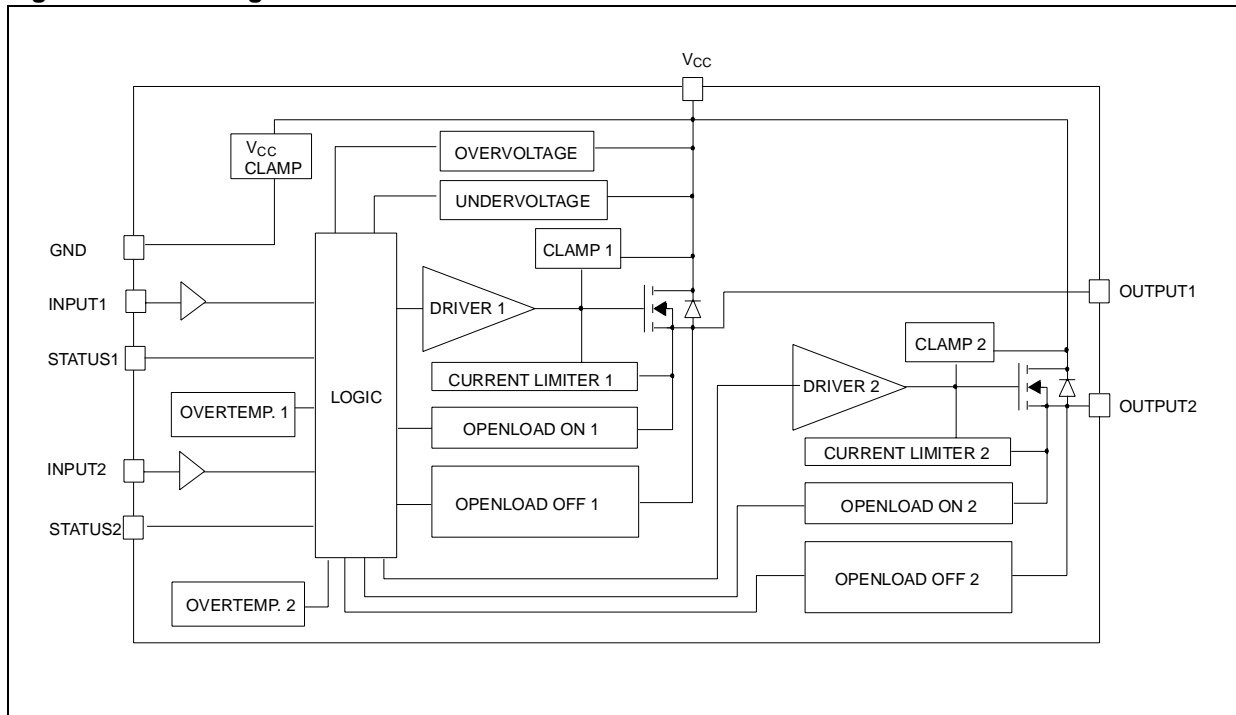


Table 3. Absolute Maximum Ratings

| Symbol             | Parameter  | Value              | Unit |
|--------------------|--|--------------------|------|
| V <sub>CC</sub>    | DC Supply Voltage  | 41                 | V    |
| - V <sub>CC</sub>  | Reverse DC Supply Voltage  | - 0.3              | V    |
| - I <sub>GND</sub> | DC Reverse Ground Pin Current  | - 200              | mA   |
| I <sub>OUT</sub>   | DC Output Current  | Internally Limited | A    |
| - I <sub>OUT</sub> | Reverse DC Output Current  | - 6                | A    |
| I <sub>IN</sub>    | DC Input Current   | +/- 10             | mA   |
| I <sub>STAT</sub>  | DC Status Current  | +/- 10             | mA   |
| V <sub>ESD</sub>   | Electrostatic Discharge (Human Body Model: R=1.5KΩ; C=100pF)   |                    |      |
|                    | - INPUT  | 4000               | V    |
|                    | - STATUS   | 4000               | V    |
|                    | - OUTPUT   | 5000               | V    |
|                    | - V <sub>CC</sub>  | 5000               | V    |
| P <sub>tot</sub>   | Power Dissipation T <sub>C</sub> =25°C   | 74                 | W    |
| E <sub>MAX</sub>   | Maximum Switching Energy<br>(L=0.14mH; R <sub>L</sub> =0Ω; V <sub>bat</sub> =13.5V; T <sub>jstart</sub> =150°C; I <sub>L</sub> =14A) | 52                 | mJ   |
| T <sub>j</sub>     | Junction Operating Temperature   | Internally Limited | °C   |
| T <sub>C</sub>     | Case Operating Temperature   | - 40 to 150        | °C   |
| T <sub>stg</sub>   | Storage Temperature  | - 55 to 150        | °C   |

Figure 3. Configuration Diagram (Top View) & Suggested Connections for Unused and N.C. Pins

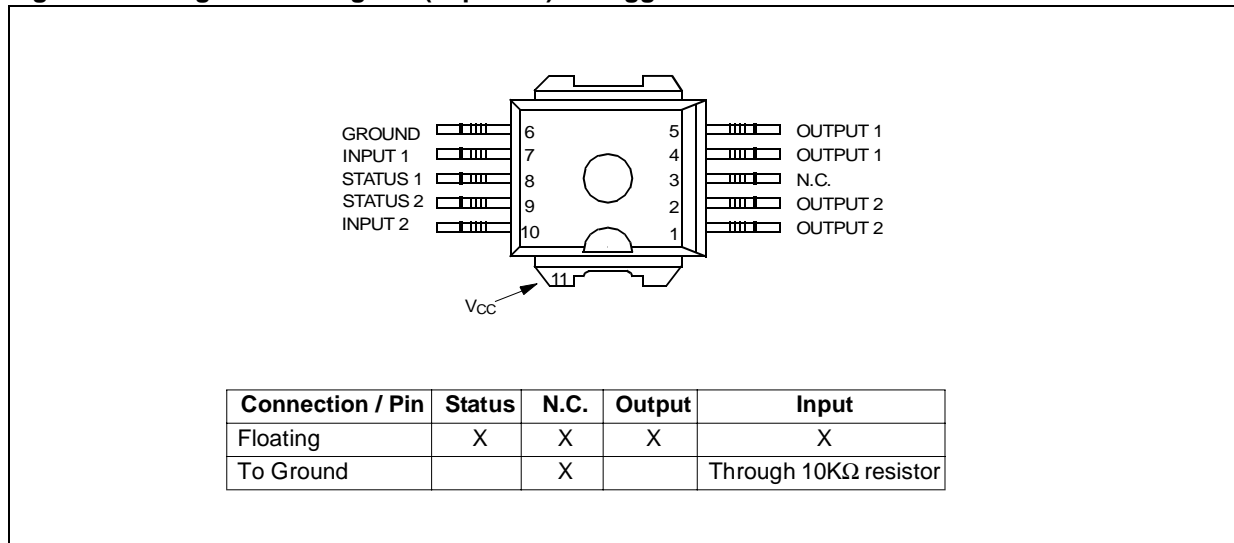


Figure 4. Current and Voltage Conventions

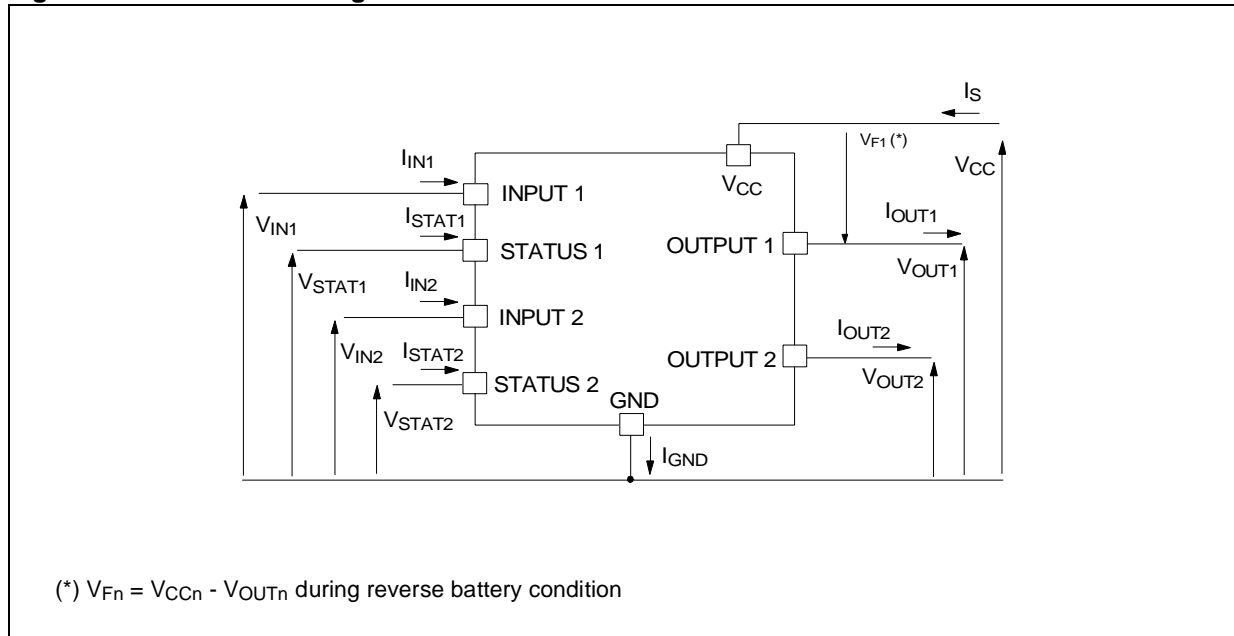


Table 4. Thermal Data

| Symbol                | Parameter                           | Value                                 | Unit |
|-----------------------|-------------------------------------|---------------------------------------|------|
| R <sub>thj-case</sub> | Thermal Resistance Junction-case    | 2                                     | °C/W |
| R <sub>thj-amb</sub>  | Thermal Resistance Junction-ambient | 52 <sup>(1)</sup>   37 <sup>(2)</sup> | °C/W |

Note: 1. When mounted on a standard single-sided FR-4 board with 0.5 cm<sup>2</sup> of Cu (at least 35μm thick). Horizontal mounting and no artificial air flow.

Note: 2. When mounted on a standard single-sided FR-4 board with 6 cm<sup>2</sup> of Cu (at least 35μm thick). Horizontal mounting and no artificial air flow.

**ELECTRICAL CHARACTERISTICS**

 (8V < V<sub>CC</sub> < 36V; -40°C < T<sub>j</sub> < 150°C, unless otherwise specified)

(Per each channel)

**Table 5. Power Output**

| Symbol                | Parameter                | Test Conditions   | Min. | Typ.          | Max.          | Unit           |
|-----------------------|--------------------------|---|------|---------------|---------------|----------------|
| V <sub>CC</sub> (**)  | Operating Supply Voltage |   | 5.5  | 13            | 36            | V              |
| V <sub>USD</sub> (**) | Undervoltage Shut-down   |   | 3    | 4             | 5.5           | V              |
| V <sub>OV</sub> (**)  | Overvoltage Shut-down    |   | 36   |               |               | V              |
| R <sub>ON</sub>       | On State Resistance      | I <sub>OUT</sub> = 2A; T <sub>j</sub> = 25°C<br>I <sub>OUT</sub> = 2A; V <sub>CC</sub> > 8V   |      |               | 60<br>120     | mΩ<br>mΩ       |
| I <sub>S</sub> (**)   | Supply Current           | Off State; V <sub>CC</sub> = 13V; V <sub>IN</sub> = V <sub>OUT</sub> = 0V<br>Off State; V <sub>CC</sub> = 13V; T <sub>j</sub> = 25°C;<br>V <sub>IN</sub> = V <sub>OUT</sub> = 0V<br>On State; V <sub>CC</sub> = 13V |      | 12<br>12<br>5 | 40<br>25<br>7 | μA<br>μA<br>mA |
| I <sub>L(off1)</sub>  | Off State Output Current | V <sub>IN</sub> = V <sub>OUT</sub> = 0V; V <sub>CC</sub> = 36V; T <sub>j</sub> = 125°C  | 0    |               | 50            | μA             |
| I <sub>L(off2)</sub>  | Off State Output Current | V <sub>IN</sub> = 0V; V <sub>OUT</sub> = 3.5V   | -75  |               | 0             | μA             |
| I <sub>L(off3)</sub>  | Off State Output Current | V <sub>IN</sub> = V <sub>OUT</sub> = 0V; V <sub>CC</sub> = 13V; T <sub>j</sub> = 125°C  |      |               | 5             | μA             |
| I <sub>L(off4)</sub>  | Off State Output Current | V <sub>IN</sub> = V <sub>OUT</sub> = 0V; V <sub>CC</sub> = 13V; T <sub>j</sub> = 25°C   |      |               | 3             | μA             |

Note: (\*\*) Per device.

**Table 6. Protection (see note 1)**

| Symbol             | Parameter                           | Test Conditions                                       | Min.                 | Typ.                 | Max.                 | Unit   |
|--------------------|-------------------------------------|---|----------------------|----------------------|----------------------|--------|
| T <sub>TSD</sub>   | Shut-down Temperature               |   | 150                  | 175                  | 200                  | °C     |
| T <sub>R</sub>     | Reset Temperature                   |   | 135                  |                      |                      | °C     |
| T <sub>hyst</sub>  | Thermal Hysteresis                  |   | 7                    | 15                   |                      | °C     |
| t <sub>SDL</sub>   | Status Delay in Overload Conditions | T <sub>j</sub> > T <sub>TSD</sub>                     |                      |                      | 20                   | μs     |
| I <sub>lim</sub>   | Current limitation                  | V <sub>CC</sub> = 13V<br>5.5V < V <sub>CC</sub> < 36V | 18                   | 23                   | 29<br>29             | A<br>A |
| V <sub>demag</sub> | Turn-off Output Clamp Voltage       | I <sub>OUT</sub> = 2A; L = 6mH                        | V <sub>CC</sub> - 41 | V <sub>CC</sub> - 48 | V <sub>CC</sub> - 55 | V      |

Note: 1. To ensure long term reliability under heavy overload or short circuit conditions, protection and related diagnostic signals must be used together with a proper software strategy. If the device is subjected to abnormal conditions, this software must limit the duration and number of activation cycles

**Table 7. V<sub>CC</sub> - Output Diode**

| Symbol         | Parameter          | Test Conditions                                  | Min | Typ | Max | Unit |
|----------------|--------------------|--|-----|-----|-----|------|
| V <sub>F</sub> | Forward on Voltage | -I <sub>OUT</sub> = 1.3A; T <sub>j</sub> = 150°C |     |     | 0.6 | V    |

**ELECTRICAL CHARACTERISTICS** (continued)**Table 8. Status Pin**

| Symbol             | Parameter                    | Test Conditions                          | Min | Typ  | Max | Unit |
|--------------------|------------------------------|--|-----|------|-----|------|
| V <sub>STAT</sub>  | Status Low Output Voltage    | I <sub>STAT</sub> = 1.6 mA               |     |      | 0.5 | V    |
| I <sub>LSTAT</sub> | Status Leakage Current       | Normal Operation; V <sub>STAT</sub> = 5V |     |      | 10  | μA   |
| C <sub>STAT</sub>  | Status Pin Input Capacitance | Normal Operation; V <sub>STAT</sub> = 5V |     |      | 100 | pF   |
| V <sub>SCL</sub>   | Status Clamp Voltage         | I <sub>STAT</sub> = 1 mA                 | 6   | 6.8  | 8   | V    |
|                    |                              | I <sub>STAT</sub> = -1 mA                |     | -0.7 |     | V    |

**Table 9. Switching** (V<sub>CC</sub>=13V)

| Symbol                                 | Parameter              | Test Conditions  | Min | Typ                  | Max | Unit |
|--|------------------------|--|-----|----------------------|-----|------|
| t <sub>d(on)</sub>                     | Turn-on Delay Time     | R <sub>L</sub> =13Ω from V <sub>IN</sub> rising edge to V <sub>OUT</sub> =1.3V   |     | 30                   |     | μs   |
| t <sub>d(off)</sub>                    | Turn-off Delay Time    | R <sub>L</sub> =13Ω from V <sub>IN</sub> falling edge to V <sub>OUT</sub> =11.7V |     | 30                   |     | μs   |
| dV <sub>OUT</sub> /dt <sub>(on)</sub>  | Turn-on Voltage Slope  | R <sub>L</sub> =13Ω from V <sub>OUT</sub> =1.3V to V <sub>OUT</sub> =10.4V       |     | See relative diagram |     | V/μs |
| dV <sub>OUT</sub> /dt <sub>(off)</sub> | Turn-off Voltage Slope | R <sub>L</sub> =13Ω from V <sub>OUT</sub> =11.7V to V <sub>OUT</sub> =1.3V       |     | See relative diagram |     | V/μs |

**Table 10. Openload Detection**

| Symbol                | Parameter                                      | Test Conditions      | Min | Typ | Max  | Unit |
|-----------------------|--|----------------------|-----|-----|------|------|
| I <sub>OL</sub>       | Openload ON State Detection Threshold          | V <sub>IN</sub> =5V  | 0.6 | 0.9 | 1.2  | A    |
| t <sub>DOL(on)</sub>  | Openload ON State Detection Delay              | I <sub>OUT</sub> =0A |     |     | 200  | μs   |
| V <sub>OL</sub>       | Openload OFF State Voltage Detection Threshold | V <sub>IN</sub> =0V  | 1.5 | 2.5 | 3.5  | V    |
| T <sub>DOL(off)</sub> | Openload Detection Delay at Turn Off           |                      |     |     | 1000 | μs   |

**Table 11. Logic Input**

| Symbol               | Parameter                | Test Conditions         | Min  | Typ  | Max  | Unit |
|----------------------|--------------------------|-------------------------|------|------|------|------|
| V <sub>IL</sub>      | Input Low Level          |                         |      |      | 1.25 | V    |
| I <sub>IL</sub>      | Low Level Input Current  | V <sub>IN</sub> = 1.25V | 1    |      |      | μA   |
| V <sub>IH</sub>      | Input High Level         |                         | 3.25 |      |      | V    |
| I <sub>IH</sub>      | High Level Input Current | V <sub>IN</sub> = 3.25V |      |      | 10   | μA   |
| V <sub>I(hyst)</sub> | Input Hysteresis Voltage |                         | 0.5  |      |      | V    |
| V <sub>ICL</sub>     | Input Clamp Voltage      | I <sub>IN</sub> = 1 mA  | 6    | 6.8  | 8    | V    |
|                      |                          | I <sub>IN</sub> = -1 mA |      | -0.7 |      | V    |

Figure 5.

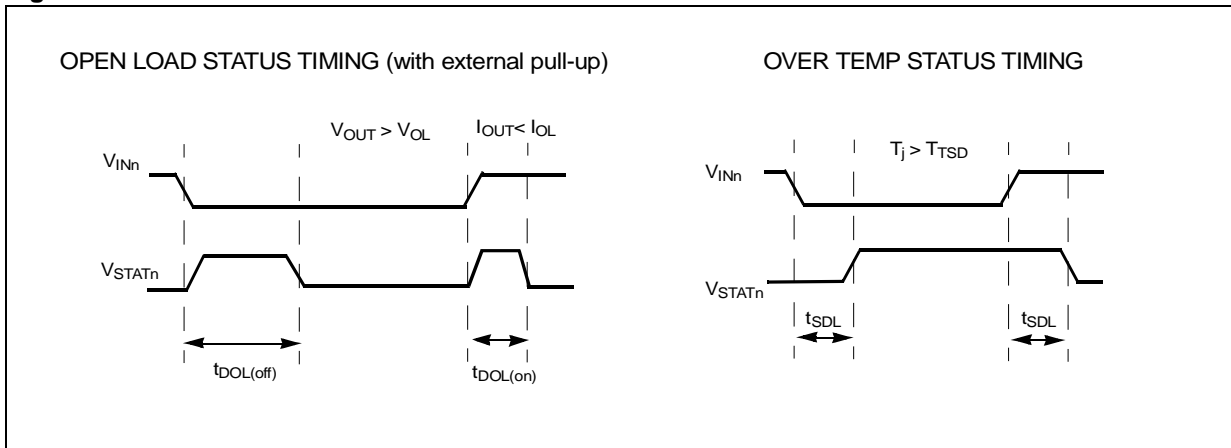


Table 12. Truth Table

| CONDITIONS                | INPUT       | OUTPUT      | SENSE   |
|---------------------------|-------------|-------------|---|
| Normal Operation          | L<br>H      | L<br>H      | H<br>H  |
| Current Limitation        | L<br>H<br>H | L<br>X<br>X | H<br>( $T_j < T_{TSD}$ ) H<br>( $T_j > T_{TSD}$ ) L |
| Overtemperature           | L<br>H      | L<br>L      | H<br>L  |
| Undervoltage              | L<br>H      | L<br>L      | X<br>X  |
| Overvoltage               | L<br>H      | L<br>L      | H<br>H  |
| Output Voltage > $V_{OL}$ | L<br>H      | H<br>H      | L<br>H  |
| Output Current < $I_{OL}$ | L<br>H      | L<br>H      | H<br>L  |

Figure 6. Switching Time Waveforms

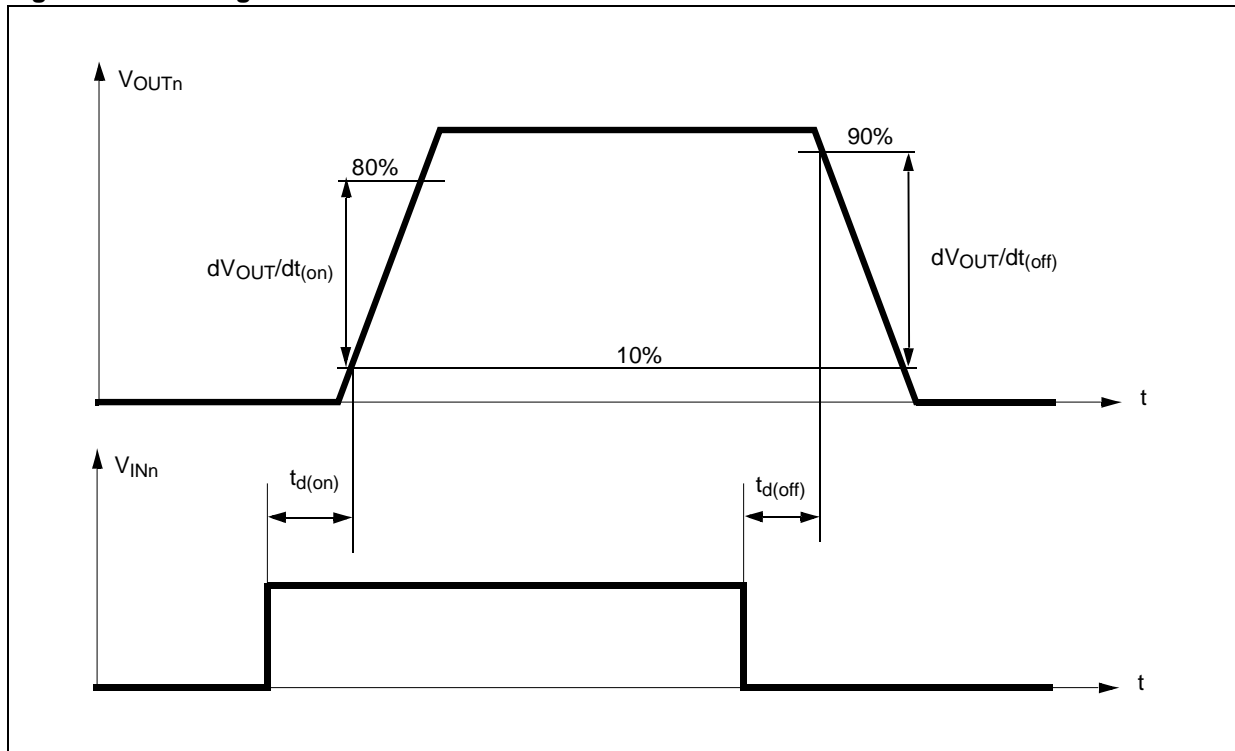


Table 13. Electrical Transient Requirements On V<sub>CC</sub> Pin

| ISO T/R 7637/1<br>Test Pulse | TEST LEVELS |         |         |         | Delays and Impedance |
|------------------------------|-------------|---------|---------|---------|----------------------|
|                              | I           | II      | III     | IV      |                      |
| 1                            | -25 V       | -50 V   | -75 V   | -100 V  | 2 ms 10 Ω            |
| 2                            | +25 V       | +50 V   | +75 V   | +100 V  | 0.2 ms 10 Ω          |
| 3a                           | -25 V       | -50 V   | -100 V  | -150 V  | 0.1 μs 50 Ω          |
| 3b                           | +25 V       | +50 V   | +75 V   | +100 V  | 0.1 μs 50 Ω          |
| 4                            | -4 V        | -5 V    | -6 V    | -7 V    | 100 ms, 0.01 Ω       |
| 5                            | +26.5 V     | +46.5 V | +66.5 V | +86.5 V | 400 ms, 2 Ω          |

| ISO T/R 7637/1<br>Test Pulse | TEST LEVELS RESULTS |    |     |    |
|------------------------------|---------------------|----|-----|----|
|                              | I                   | II | III | IV |
| 1                            | C                   | C  | C   | C  |
| 2                            | C                   | C  | C   | C  |
| 3a                           | C                   | C  | C   | C  |
| 3b                           | C                   | C  | C   | C  |
| 4                            | C                   | C  | C   | C  |
| 5                            | C                   | E  | E   | E  |

| CLASS | CONTENTS   |
|-------|--|
| C     | All functions of the device are performed as designed after exposure to disturbance.   |
| E     | One or more functions of the device is not performed as designed after exposure and cannot be returned to proper operation without replacing the device. |

Figure 7. Waveforms

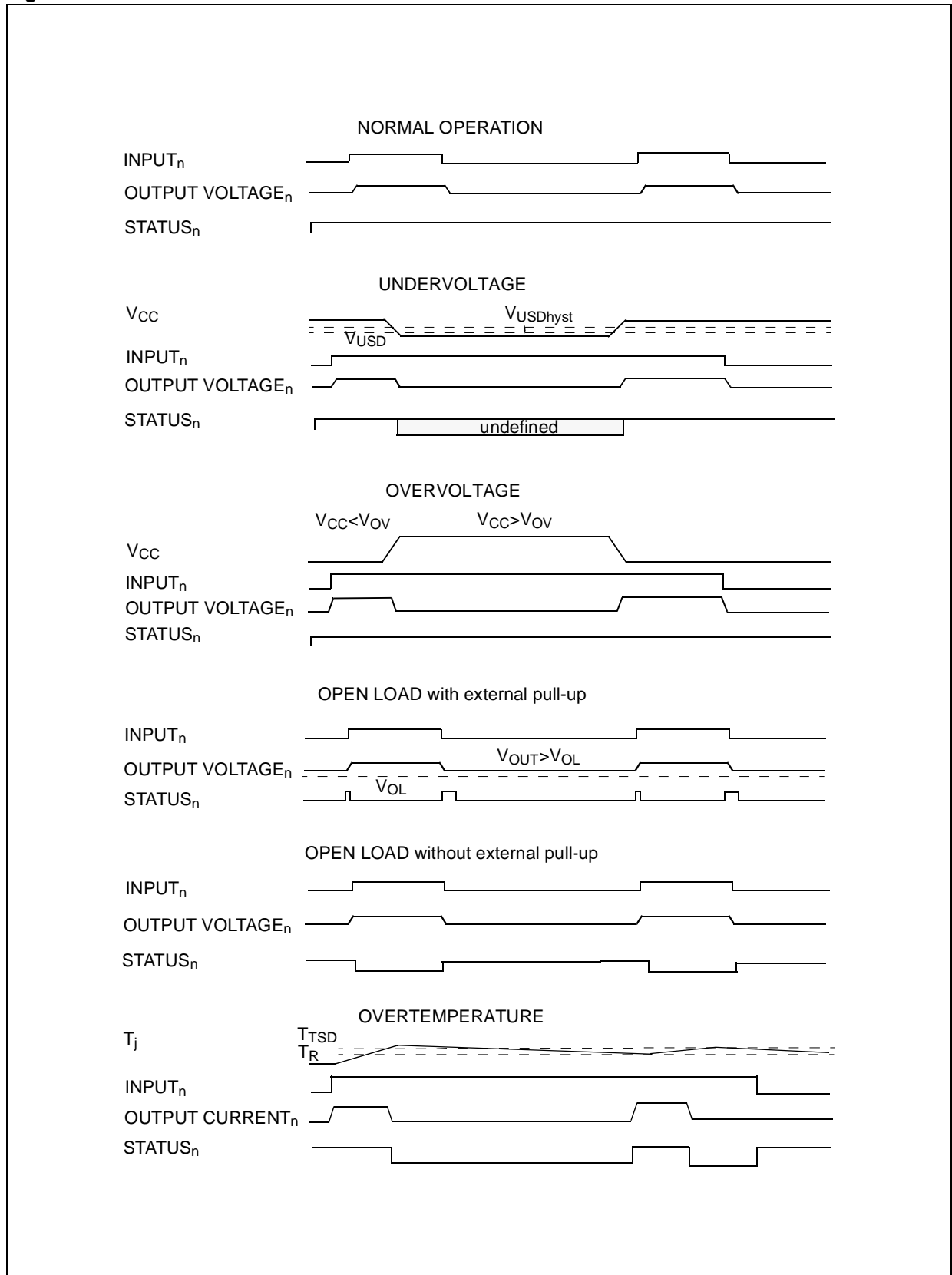
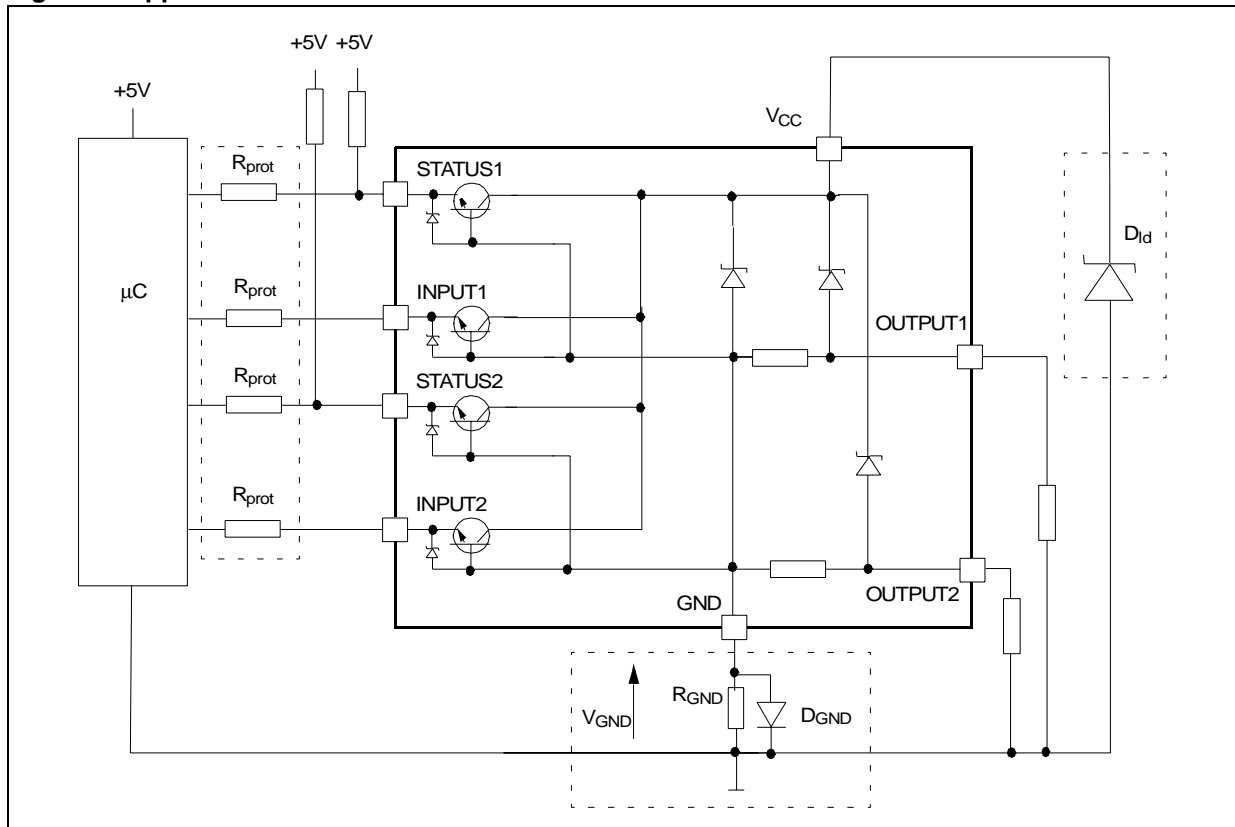




Figure 8. Application Schematic



### GND PROTECTION NETWORK AGAINST REVERSE BATTERY

**Solution 1:** Resistor in the ground line ( $R_{GND}$  only). This can be used with any type of load.

The following is an indication on how to dimension the  $R_{GND}$  resistor.

- 1)  $R_{GND} \leq 600\text{mV} / I_{S(on)max}$ .
- 2)  $R_{GND} \geq (-V_{CC}) / (-I_{GND})$

where  $-I_{GND}$  is the DC reverse ground pin current and can be found in the absolute maximum rating section of the device's datasheet.

Power Dissipation in  $R_{GND}$  (when  $V_{CC} < 0$ : during reverse battery situations) is:

$$P_D = (-V_{CC})^2 / R_{GND}$$

This resistor can be shared amongst several different HSD. Please note that the value of this resistor should be calculated with formula (1) where  $I_{S(on)max}$  becomes the sum of the maximum on-state currents of the different devices.

Please note that if the microprocessor ground is not common with the device ground then the  $R_{GND}$  will produce a shift ( $I_{S(on)max} * R_{GND}$ ) in the input thresholds and the status output values.

This shift will vary depending on how many devices are ON in the case of several high side drivers sharing the same  $R_{GND}$ .

If the calculated power dissipation leads to a large resistor or several devices have to share the same

resistor then the ST suggests to utilize Solution 2 (see below).

**Solution 2:** A diode ( $D_{GND}$ ) in the ground line.

A resistor ( $R_{GND} = 1\text{k}\Omega$ ) should be inserted in parallel to  $D_{GND}$  if the device will be driving an inductive load.

This small signal diode can be safely shared amongst several different HSD. Also in this case, the presence of the ground network will produce a shift ( $\approx 600\text{mV}$ ) in the input threshold and the status output values if the microprocessor ground is not common with the device ground. This shift will not vary if more than one HSD shares the same diode/resistor network.

Series resistor in INPUT and STATUS lines are also required to prevent that, during battery voltage transient, the current exceeds the Absolute Maximum Rating.

Safest configuration for unused INPUT and STATUS pin is to leave them unconnected.

### LOAD DUMP PROTECTION

$D_{ld}$  is necessary (Voltage Transient Suppressor) if the load dump peak voltage exceeds  $V_{CC}$  max DC rating. The same applies if the device will be subject to transients on the  $V_{CC}$  line that are greater than the ones shown in the ISO T/R 7637/1 table.

### µC I/Os PROTECTION:

If a ground protection network is used and negative transient are present on the  $V_{CC}$  line, the control pins will be pulled negative. ST suggests to insert a resistor ( $R_{prot}$ ) in line to prevent the  $\mu\text{C}$  I/Os pins to latch-up.

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The value of these resistors is a compromise between the leakage current of  $\mu\text{C}$  and the current required by the HSD I/Os (Input levels compatibility) with the latch-up limit of  $\mu\text{C}$  I/Os.

$$-V_{CC\text{peak}}/I_{\text{latchup}} \leq R_{\text{prot}} \leq (V_{OH\mu\text{C}} - V_{IH} - V_{GND}) / I_{IH\text{max}}$$

Calculation example:

For  $V_{CC\text{peak}} = -100\text{V}$  and  $I_{\text{latchup}} \geq 20\text{mA}$ ;  $V_{OH\mu\text{C}} \geq 4.5\text{V}$   
 $5\text{k}\Omega \leq R_{\text{prot}} \leq 65\text{k}\Omega$ .

Recommended  $R_{\text{prot}}$  value is  $10\text{k}\Omega$ .

### OPEN LOAD DETECTION IN OFF STATE

Off state open load detection requires an external pull-up resistor ( $R_{\text{PU}}$ ) connected between OUTPUT pin and a positive supply voltage ( $V_{\text{PU}}$ ) like the +5V line used to supply the microprocessor.

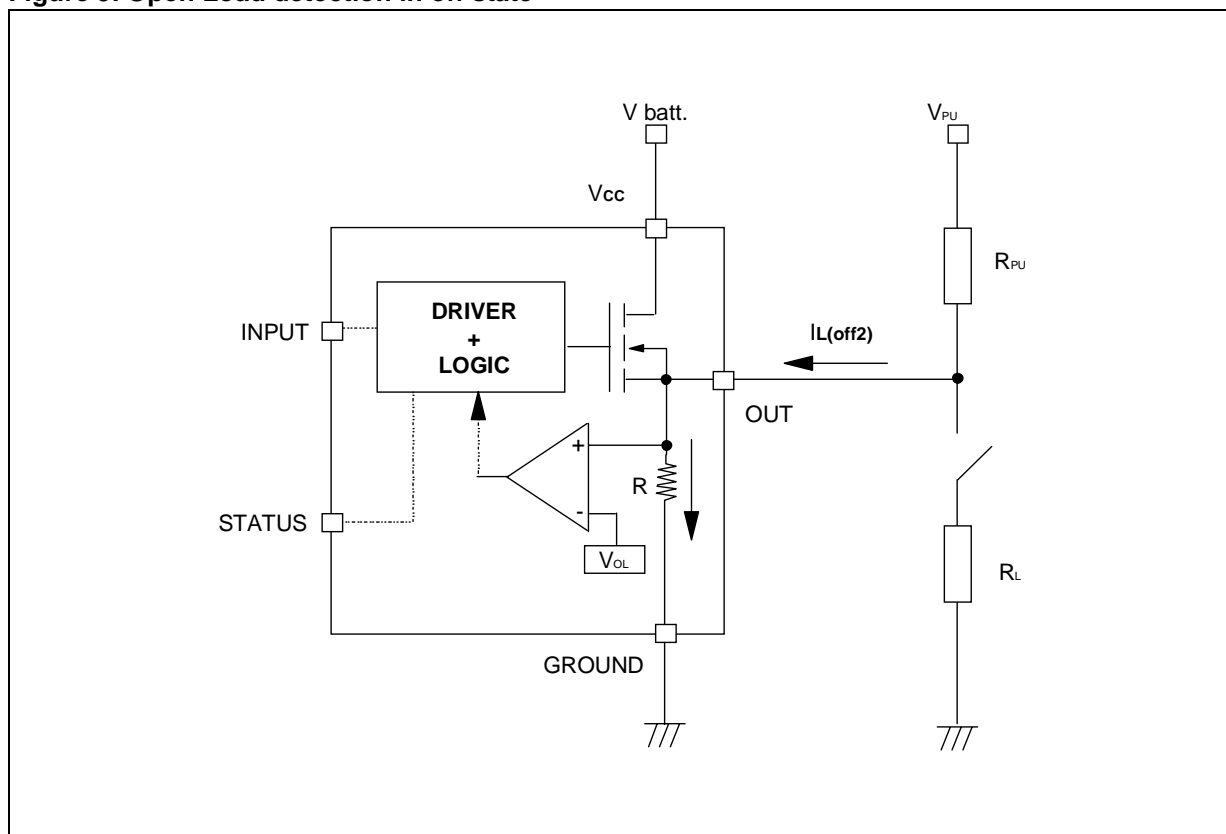
The external resistor has to be selected according to the following requirements:

- 1) no false open load indication when load is connected: in this case we have to avoid  $V_{\text{OUT}}$  to be higher than  $V_{\text{OLmin}}$ ; this results in the following condition  $V_{\text{OUT}} = (V_{\text{PU}} / (R_{\text{L}} + R_{\text{PU}})) R_{\text{L}} < V_{\text{OLmin}}$ .
- 2) no misdetection when load is disconnected: in this case the  $V_{\text{OUT}}$  has to be higher than  $V_{\text{OLmax}}$ ; this results in the following condition  $R_{\text{PU}} < (V_{\text{PU}} - V_{\text{OLmax}}) / I_{\text{L(off2)}}$ .

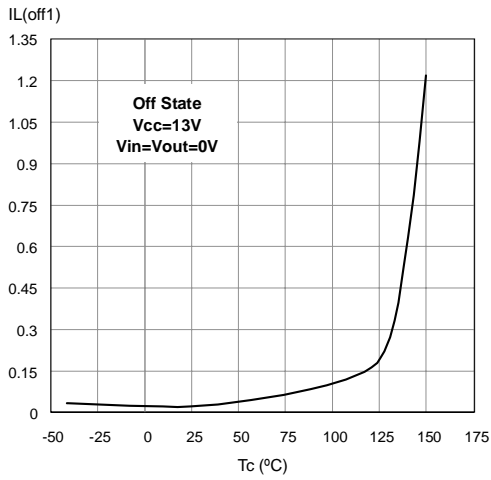
Because  $I_{\text{S(OFF)}}$  may significantly increase if  $V_{\text{out}}$  is pulled high (up to several mA), the pull-up resistor  $R_{\text{PU}}$  should be connected to a supply that is switched OFF when the module is in standby.

The values of  $V_{\text{OLmin}}$ ,  $V_{\text{OLmax}}$  and  $I_{\text{L(off2)}}$  are available in the Electrical Characteristics section.

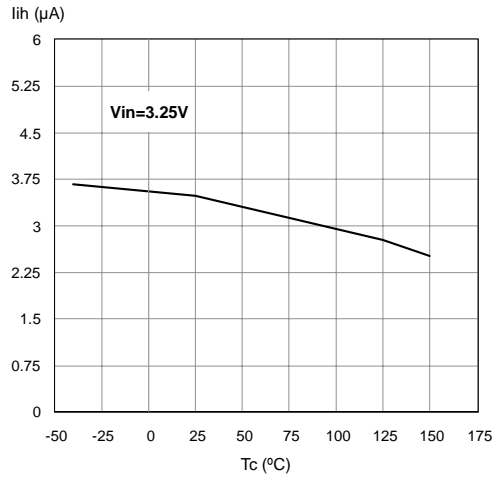
Figure 9. Open Load detection in off state



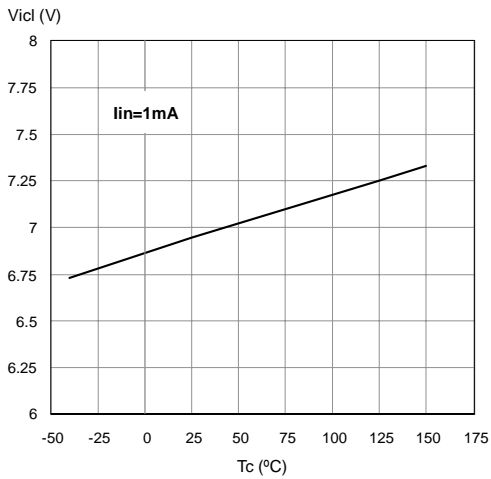
**Figure 10. Off State Output Current**



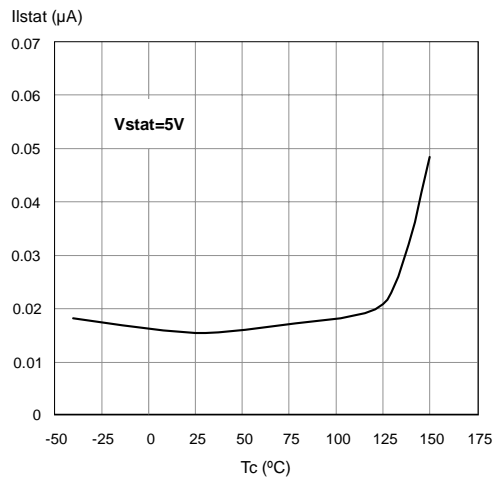
**Figure 13. High Level Input Current**



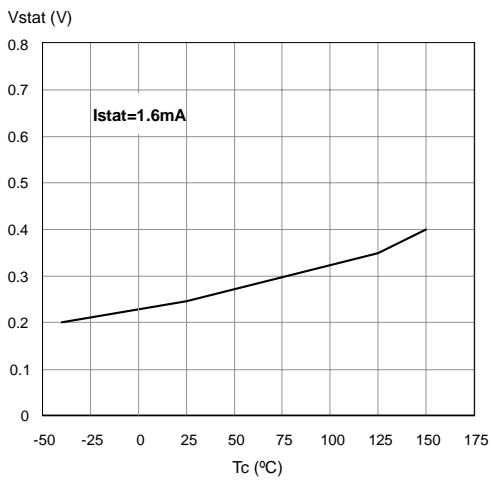
**Figure 11. Input Clamp Voltage**



**Figure 14. Status Leakage Current**



**Figure 12. Status Low Output Voltage**



**Figure 15. Status Clamp Voltage**

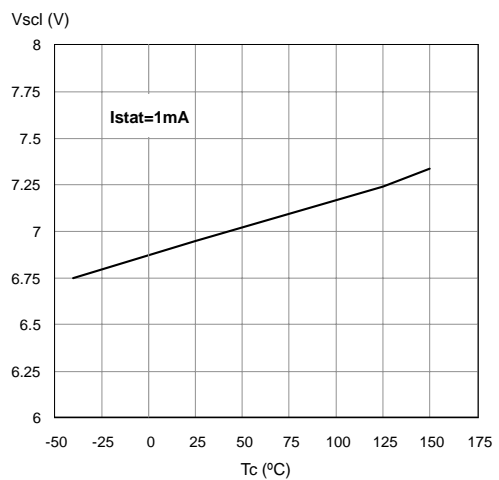


Figure 16. On State Resistance Vs  $T_{case}$

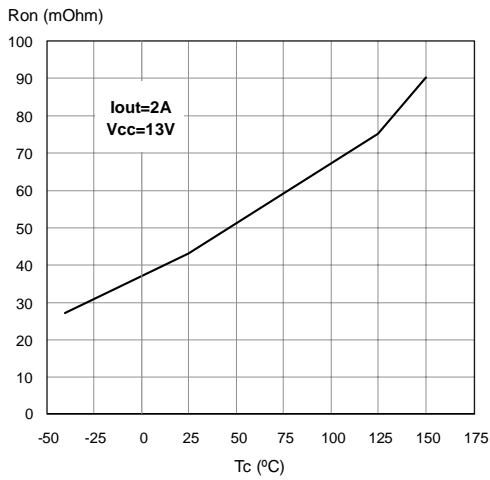


Figure 19. On State Resistance Vs  $V_{CC}$

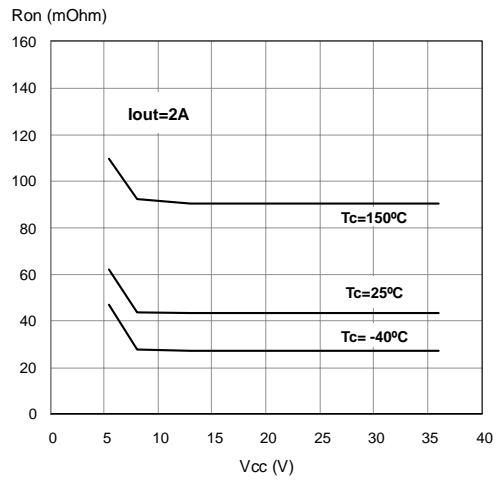


Figure 17. Openload On State Detection Threshold

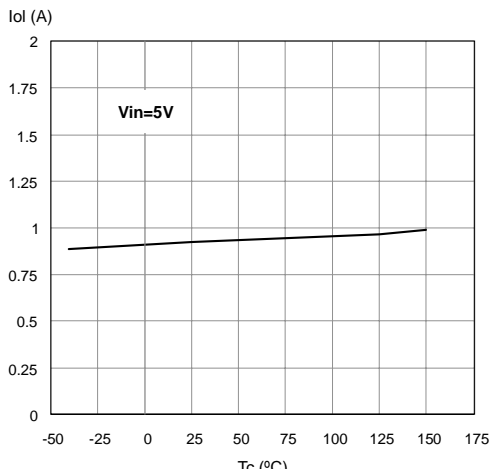


Figure 20. Openload Off State Detection Threshold

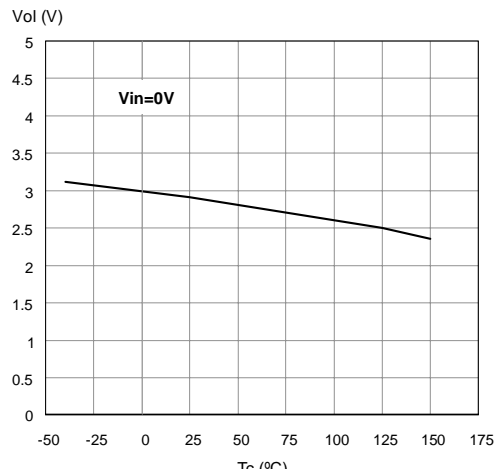


Figure 18. Input High Level

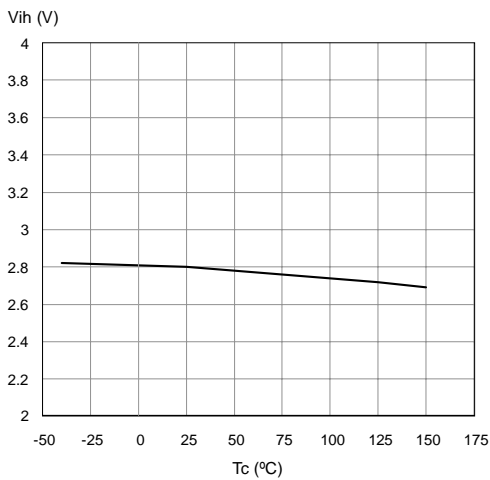


Figure 21. Input Low Level

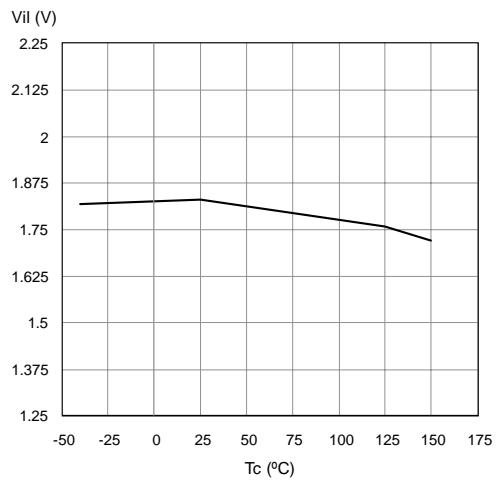


Figure 22. Input Hysteresis Voltage

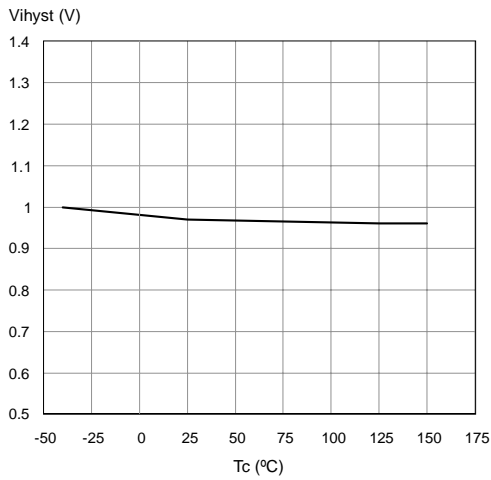


Figure 25. Overvoltage Shutdown

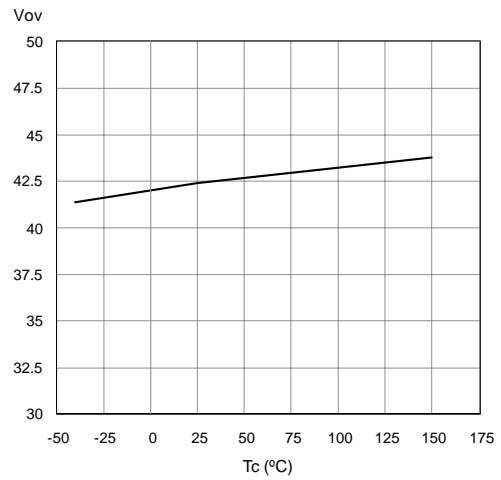


Figure 23. Turn-on Voltage Slope

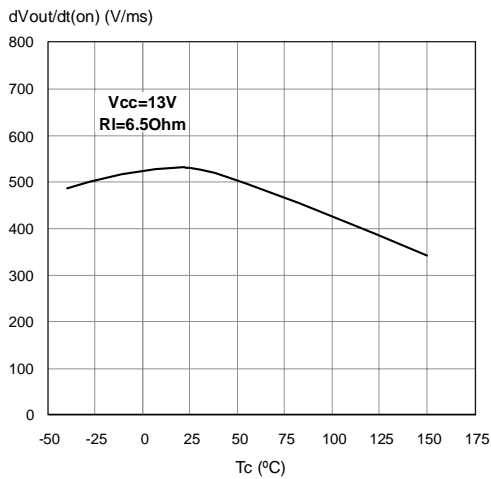


Figure 26. Turn-off Voltage Slope

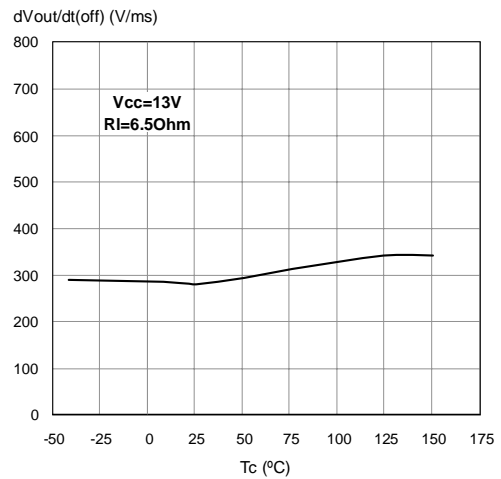


Figure 24. I<sub>LIM</sub> Vs T<sub>case</sub>

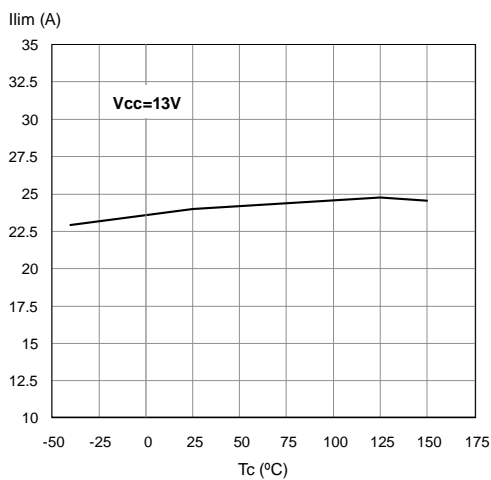
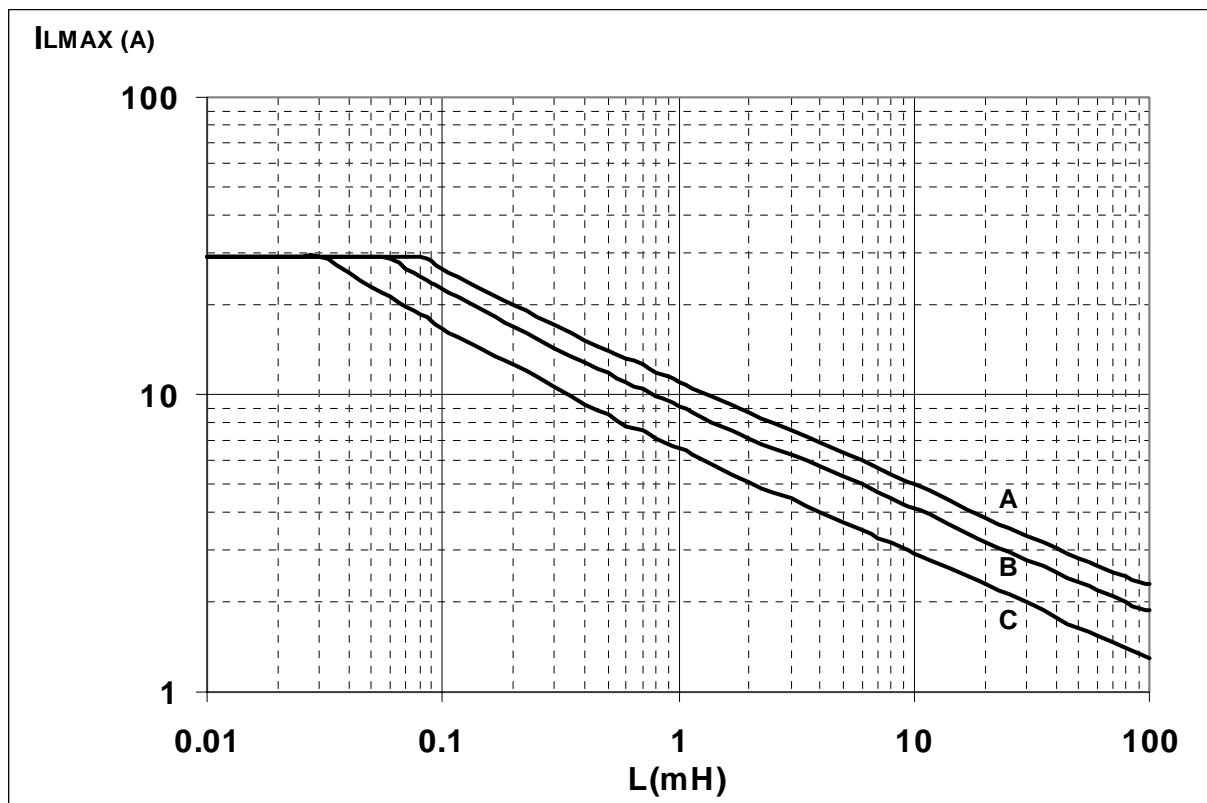


Figure 27. Maximum turn off current versus load inductance



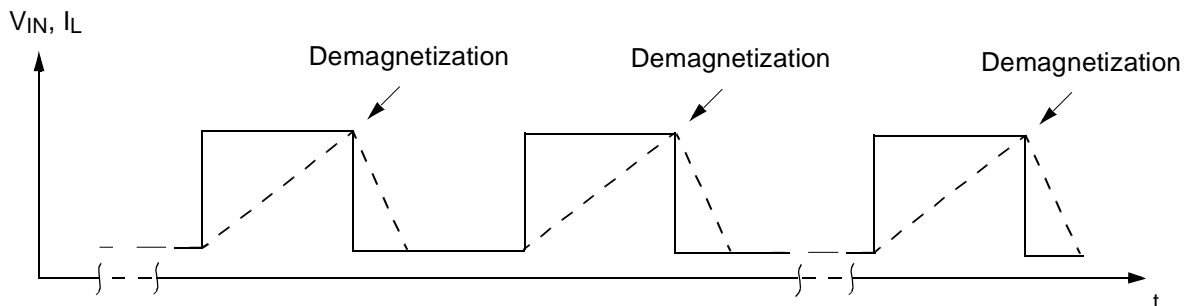
- A = Single Pulse at  $T_{Jstart}=150^{\circ}C$
- B= Repetitive pulse at  $T_{Jstart}=100^{\circ}C$
- C= Repetitive Pulse at  $T_{Jstart}=125^{\circ}C$

Values are generated with  $R_L=0\Omega$

In case of repetitive pulses,  $T_{Jstart}$  (at beginning of each demagnetization) of every pulse must not exceed the temperature specified above for curves B and C.

Conditions:

$V_{CC}=13.5V$



PowerSO-10™ Thermal Data

Figure 28. PowerSO-10™ PC Board

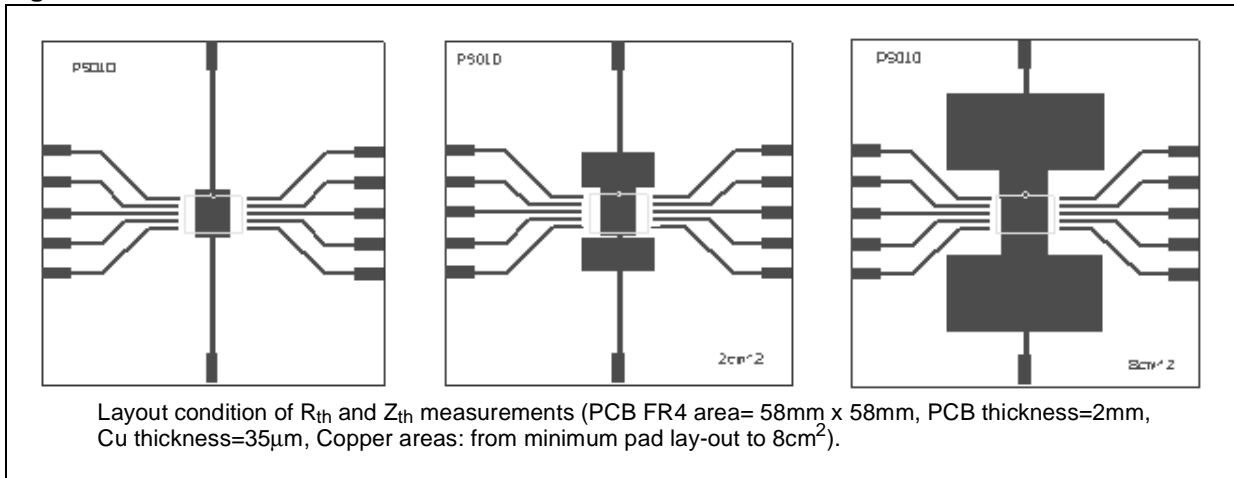


Figure 29.  $R_{thj-amb}$  Vs PCB copper area in open box free air condition

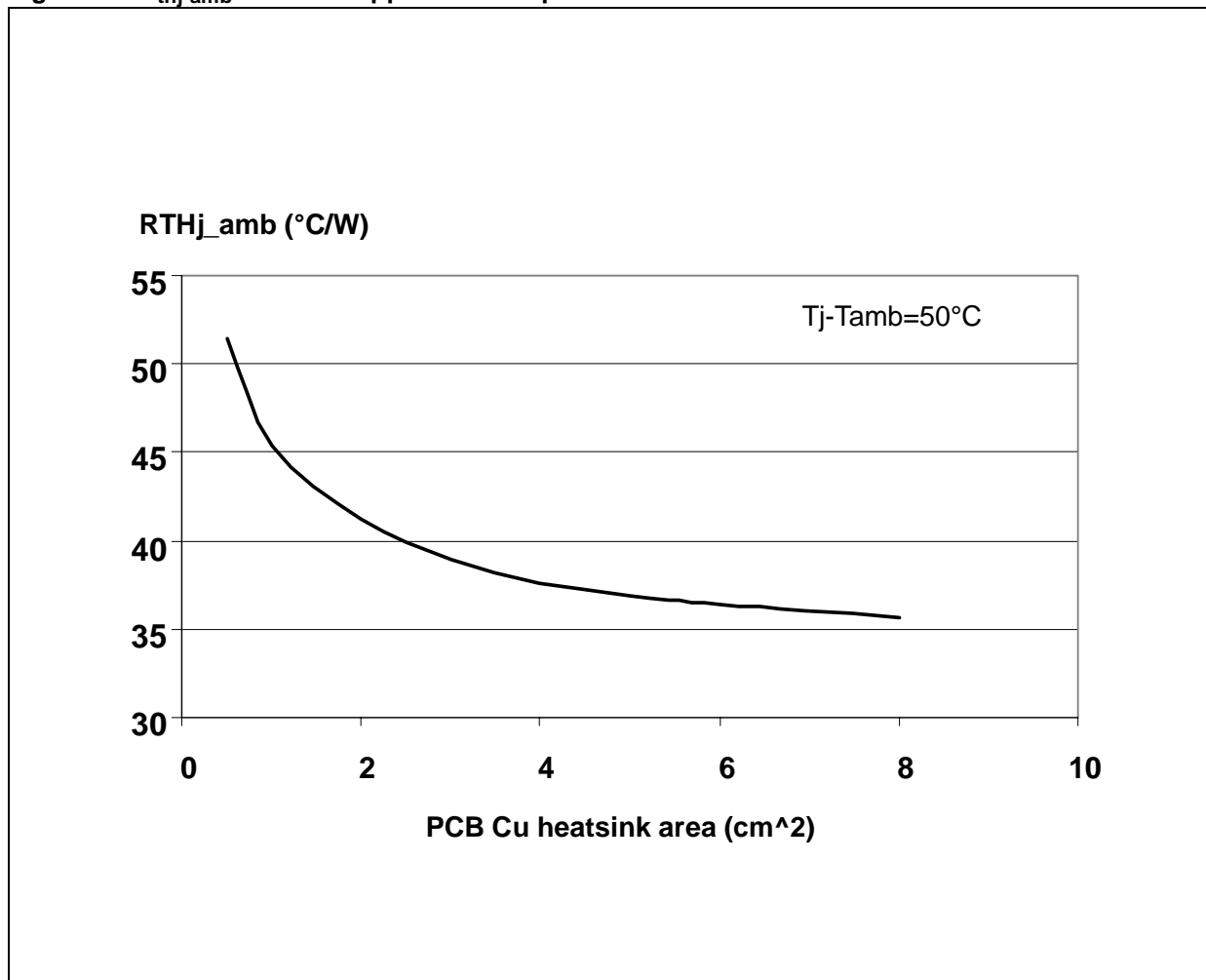


Figure 30. PowerSO-10 Thermal Impedance Junction Ambient Single Pulse

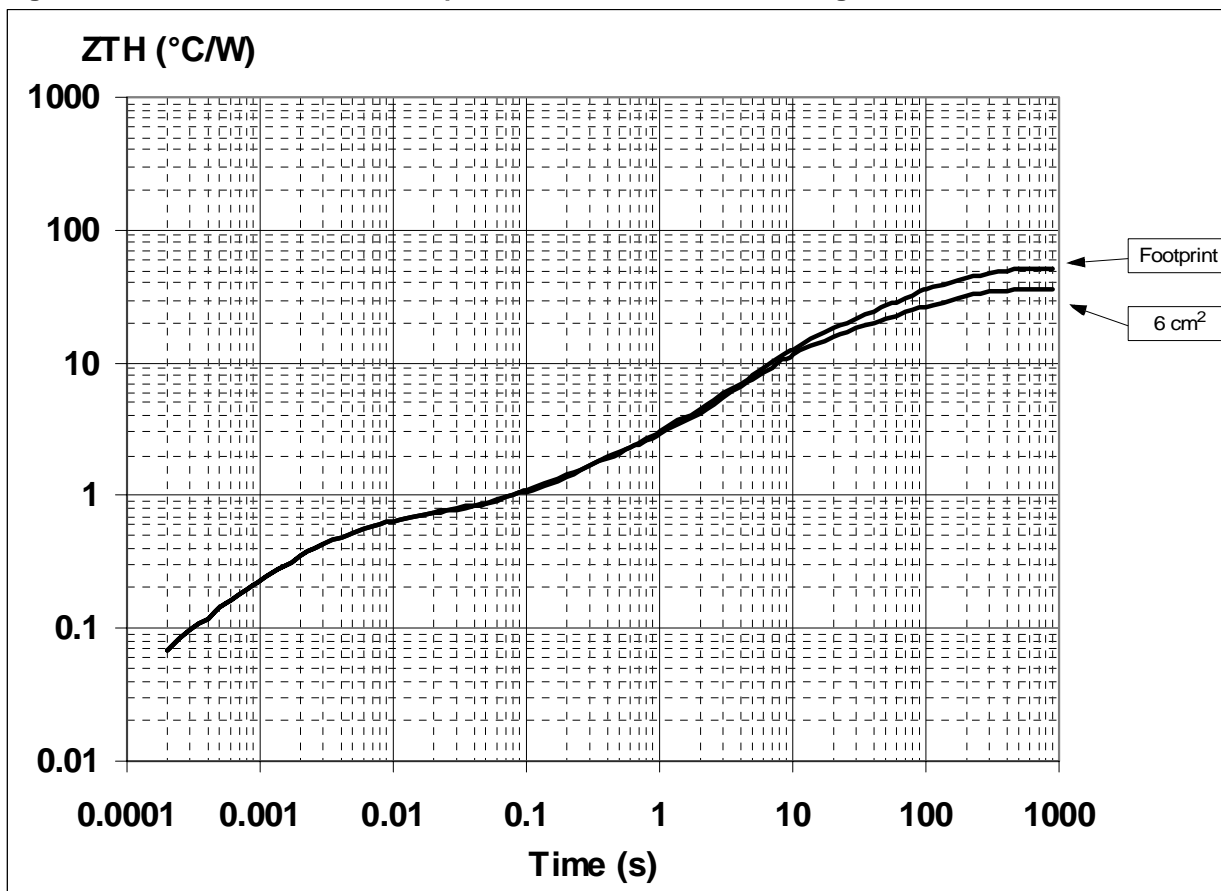
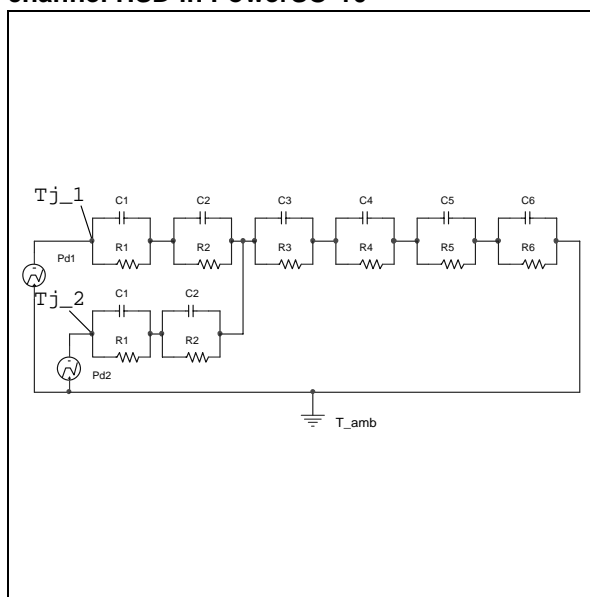


Figure 31. Thermal fitting model of a double channel HSD in PowerSO-10



Pulse calculation formula

$$Z_{TH\delta} = R_{TH} \cdot \delta + Z_{THtp}(1 - \delta)$$

where  $\delta = t_p/T$

Table 14. Thermal Parameter

| Area/island (cm <sup>2</sup> ) | Footprint | 6  |
|--------------------------------|-----------|----|
| R1 (°C/W)                      | 0.05      |    |
| R2 (°C/W)                      | 0.3       |    |
| R3 (°C/W)                      | 0.3       |    |
| R4 (°C/W)                      | 0.8       |    |
| R5 (°C/W)                      | 12        |    |
| R6 (°C/W)                      | 37        | 22 |
| C1 (W.s/°C)                    | 0.001     |    |
| C2 (W.s/°C)                    | 5.00E-03  |    |
| C3 (W.s/°C)                    | 0.02      |    |
| C4 (W.s/°C)                    | 0.3       |    |
| C5 (W.s/°C)                    | 0.75      |    |
| C6 (W.s/°C)                    | 3         | 5  |



PACKAGE MECHANICAL

Table 15. PowerSO-10™ Mechanical Data

| Symbol | millimeters |      |       |
|--------|-------------|------|-------|
|        | Min         | Typ  | Max   |
| A      | 3.35        |      | 3.65  |
| A (*)  | 3.4         |      | 3.6   |
| A1     | 0.00        |      | 0.10  |
| B      | 0.40        |      | 0.60  |
| B (*)  | 0.37        |      | 0.53  |
| C      | 0.35        |      | 0.55  |
| C (*)  | 0.23        |      | 0.32  |
| D      | 9.40        |      | 9.60  |
| D1     | 7.40        |      | 7.60  |
| E      | 9.30        |      | 9.50  |
| E2     | 7.20        |      | 7.60  |
| E2 (*) | 7.30        |      | 7.50  |
| E4     | 5.90        |      | 6.10  |
| E4 (*) | 5.90        |      | 6.30  |
| e      |             | 1.27 |       |
| F      | 1.25        |      | 1.35  |
| F (*)  | 1.20        |      | 1.40  |
| H      | 13.80       |      | 14.40 |
| H (*)  | 13.85       |      | 14.35 |
| h      |             | 0.50 |       |
| L      | 1.20        |      | 1.80  |
| L (*)  | 0.80        |      | 1.10  |
| a      | 0°          |      | 8°    |
| α (*)  | 2°          |      | 8°    |

Note: (\*) Muar only POA P013P

Figure 32. PowerSO-10™ Package Dimensions

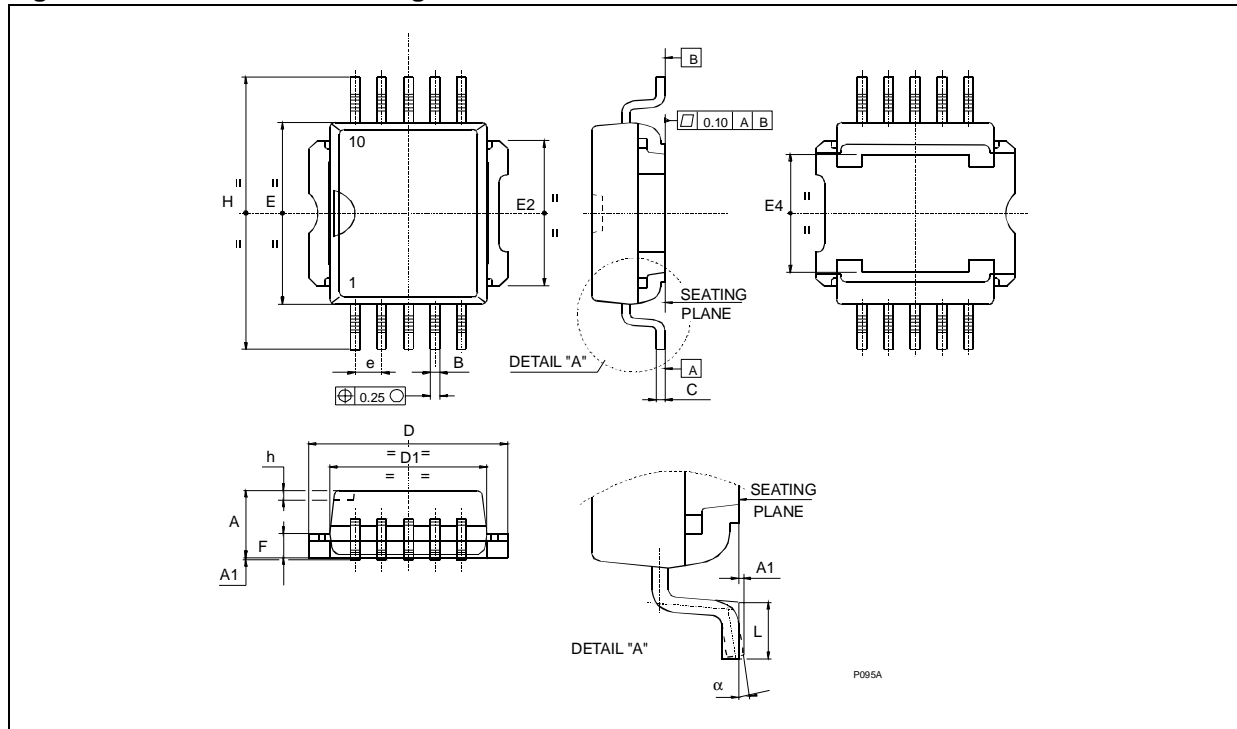


Figure 33. PowerSO-10™ Suggested Pad Layout And Tube Shipment (No Suffix)

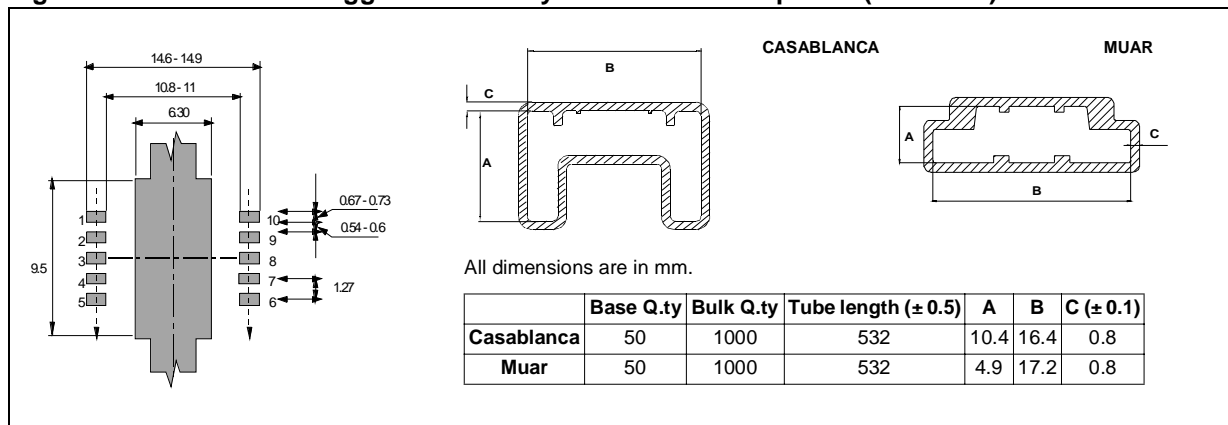
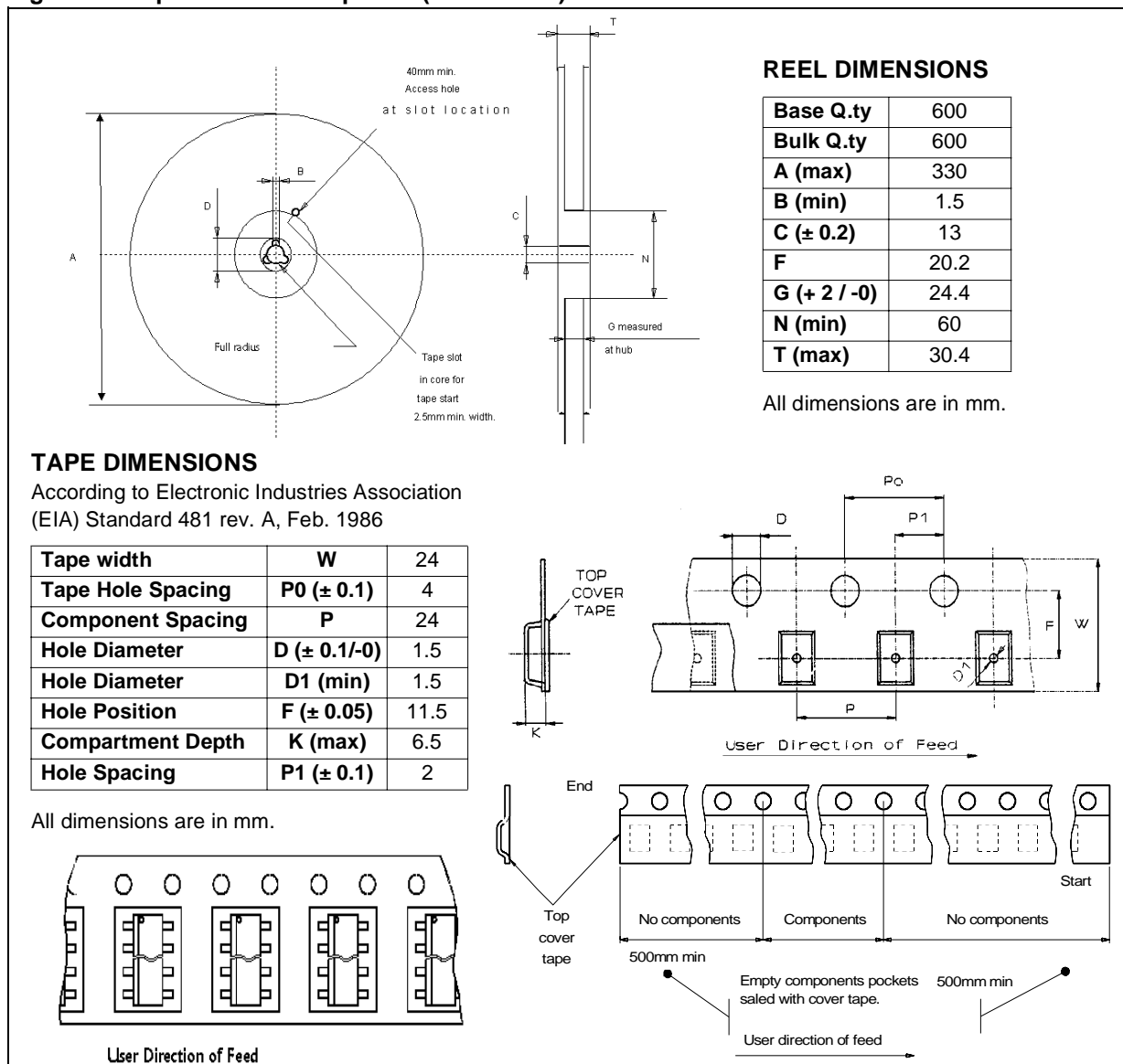


Figure 34. Tape And Reel Shipment (suffix “TR”)



**REVISION HISTORY**

| Date      | Revision | Description of Changes |
|-----------|----------|------------------------|
| Oct. 2004 | 1        | - First Issue.         |

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